



# Product End-of-Life Disassembly Instructions

Product Category: Other Products

## Marketing Name / Model

[List multiple models if applicable.]

HP DB OLM 480V 30A 10/5 IEC309, US / AF487A  
HP DB OLM 480V 30A 10/5, L22-30, US / AF486A  
HP DB OLM 380V 30A 10/5W Harm, China / AF485A  
HP DB OLM 415 30A 10/5 IEC309 US/INTL / AF484A  
HP DB OLM 415V 30A 10/5 Harm IEC309 Euro / AF483A  
HP DB OLM 415 30A 10/5 IEC309 US/INTL / D9Q02A

**Purpose:** The document is intended for use by end-of-life recyclers or treatment facilities. It provides the basic instructions for the disassembly of HP products to remove components and materials requiring selective treatment, as defined by EU directive 2002/96/EC, Waste Electrical and Electronic Equipment (WEEE).

## 1.0 Items Requiring Selective Treatment

1.1 Items listed below are classified as requiring selective treatment.

1.2 Enter the quantity of items contained within the product which require selective treatment in the right column, as applicable.

Item Description	Notes	Quantity of items included in product
Printed Circuit Boards (PCB) or Printed Circuit Assemblies (PCA)	With a surface greater than 10 sq cm	0
Batteries	All types including standard alkaline and lithium coin or button style batteries	0
Mercury-containing components	For example, mercury in lamps, display backlights, scanner lamps, switches, batteries	0
Liquid Crystal Displays (LCD) with a surface greater than 100 sq cm	Includes background illuminated displays with gas discharge lamps	0
Cathode Ray Tubes (CRT)		0
Capacitors / condensers (Containing PCB/PCT)		0
Electrolytic Capacitors / Condensers measuring greater than 2.5 cm in diameter or height		0
External electrical cables and cords		2(AF484A)/ 3(others beside AF484A)
Gas Discharge Lamps		0
Plastics containing Brominated Flame Retardants		0

weighing > 25 grams (not including PCBs or PCAs already listed as a separate item above)		
Components and parts containing toner and ink, including liquids, semi-liquids (gel/paste) and toner	Include the cartridges, print heads, tubes, vent chambers, and service stations.	0
Components and waste containing asbestos		0
Components, parts and materials containing refractory ceramic fibers		0
Components, parts and materials containing radioactive substances		0

## 2.0 Tools Required

List the type and size of the tools that would typically be used to disassemble the product to a point where components and materials requiring selective treatment can be removed.

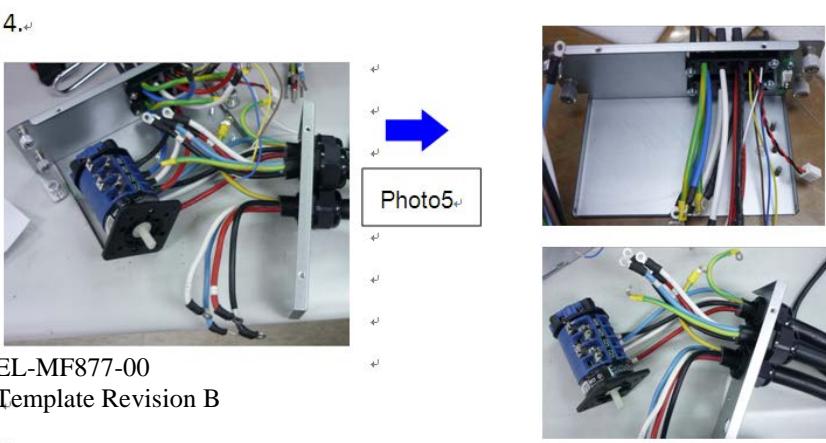
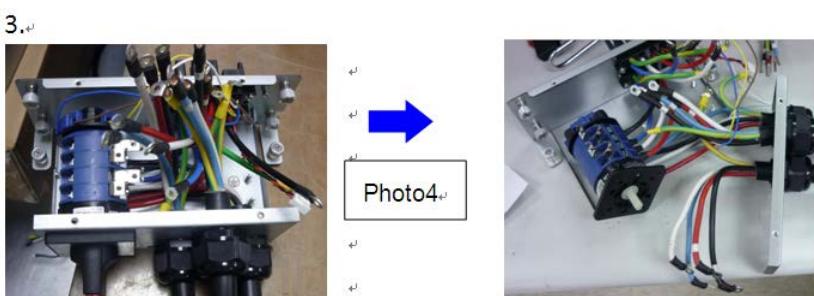
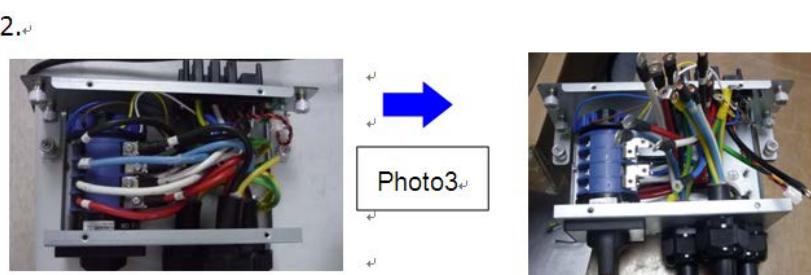
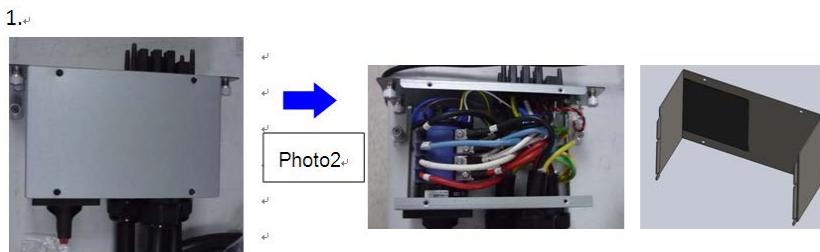
Tool Description	Tool Size (if applicable)
Description #1 Cutting Pliers	140mm
Description #2 Sleeve	210mm(M4)
Description #3 Screwdriver	260mm
Description #4 (Please refer to Photo1)	

## 3.0 Product Disassembly Process

3.1 List the basic steps that should typically be followed to remove components and materials requiring selective treatment:

1. Take off the cover.(as Photo 2)
2. Take off wires.(as Photo 3)
3. Take off the case and switch.(as Photo 4)
4. Take off wires.(as Photo 5)
- 5.
- 6.
- 7.
- 8.

3.2 Optional Graphic. If the disassembly process is complex, insert a graphic illustration below to identify the items contained in the product that require selective treatment (with descriptions and arrows identifying locations).



**PCB component**

type	component	tool	photo of example
N/A	N/A	N/A	N/A